



Description

The HXY100N02D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 20V$ $I_D = 100A$

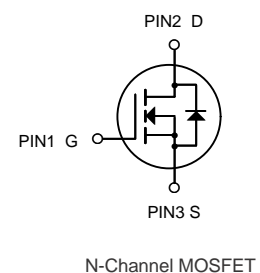
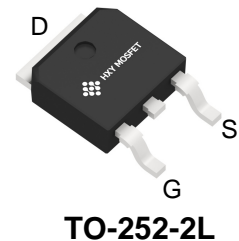
$R_{DS(ON)} < 4m\Omega$ @ $V_{GS} = 4.5V$

Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
HXY100N02D	TO-252-2L	100N02 XXX YYYY	2500

Absolute Maximum Ratings ($T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Drain Current-Continuous	100	A
$I_D(100^{\circ}C)$	Drain Current-Continuous($T_C=100^{\circ}C$)	59	A
I_{DM}	Pulsed Drain Current	360	A
P_D	Maximum Power Dissipation	88	W
E_{AS}	Single pulse avalanche energy	118	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}C$
$R_{\theta JC}$	Thermal Resistance,Junction-to-Case	1.8	$^{\circ}C/W$



Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V	-	-	1	μA
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±12V, V _{DS} =0V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.4	0.7	1.0	V
R _{DS(on)}	Static Drain-Source On-Resistance note3	V _{GS} =4.5V, I _D =30A	-	2.8	4	mΩ
		V _{GS} =2.5V, I _D =20A		4	6	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V, f=1.0MHz	-	3200	-	pF
C _{oss}	Output Capacitance		-	460	-	pF
C _{rss}	Reverse Transfer Capacitance		-	445	-	pF
Q _g	Total Gate Charge	V _{DS} =10V, I _D =30A, V _{GS} =4.5V	-	48	-	nC
Q _{gs}	Gate-Source Charge		-	3.6	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	19	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DS} =10V, I _D =30A, R _G =1.8Ω, V _{GS} =4.5V	-	9.7	-	ns
t _r	Turn-On Rise Time		-	37	-	ns
t _{d(off)}	Turn-Off Delay Time		-	63	-	ns
t _f	Turn-Off Fall Time		-	52	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	100	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	360	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _{SD} =30A, T _J =25°C	-	-	1.2	V
t _{rr}	Reverse Recovery Time	T _J =25°C, I _F =30A,	-	23	-	ns
Q _{rr}	Reverse Recovery Charge	di/dt =100A/μs	-	10	-	nC

- Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition: $T_J=25^{\circ}\text{C}$, $V_{DD}=15V$, $V_G=4.5V$, $R_G=25\Omega$, $L=0.5mH$, $I_{AS}=21A$
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$



Typical Performance Characteristics

Figure1: Output Characteristics

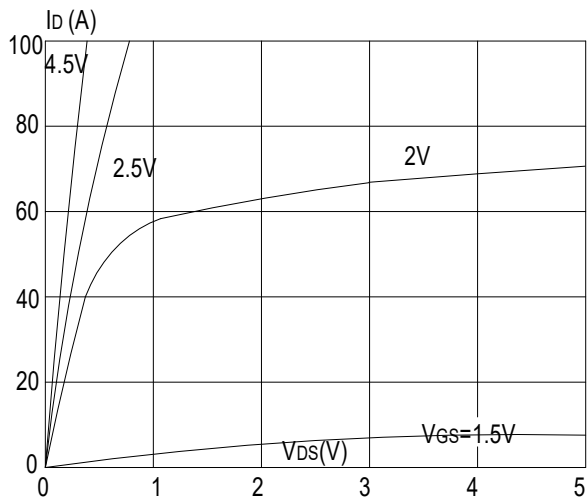


Figure 2: Typical Transfer Characteristics

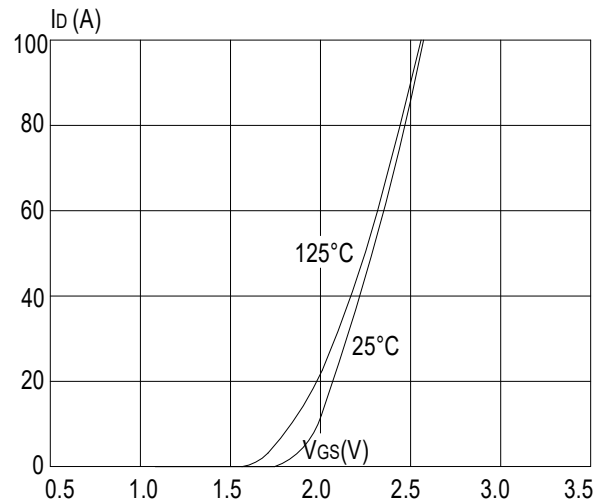


Figure 3: On-resistance vs. Drain Current

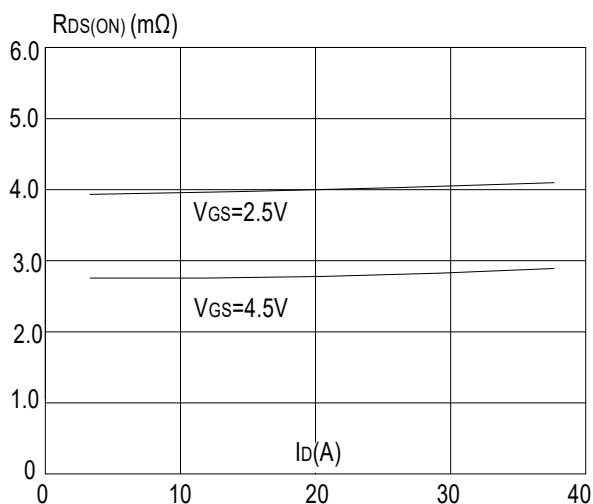


Figure 4: Body Diode Characteristics

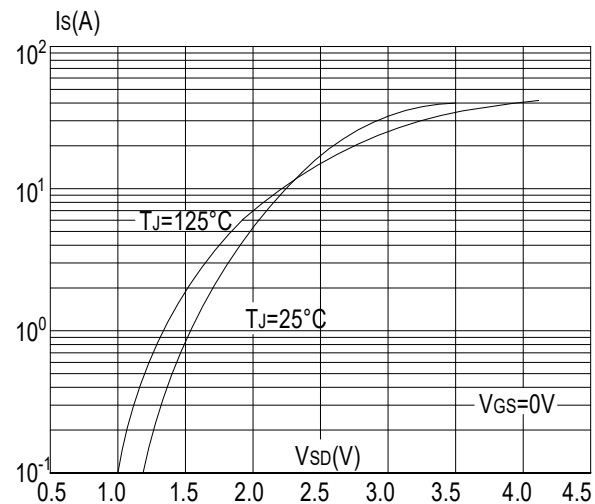


Figure 5: Gate Charge Characteristics

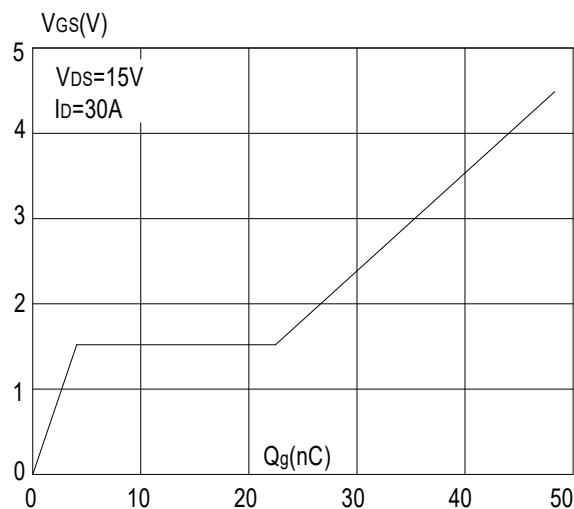


Figure 6: Capacitance Characteristics

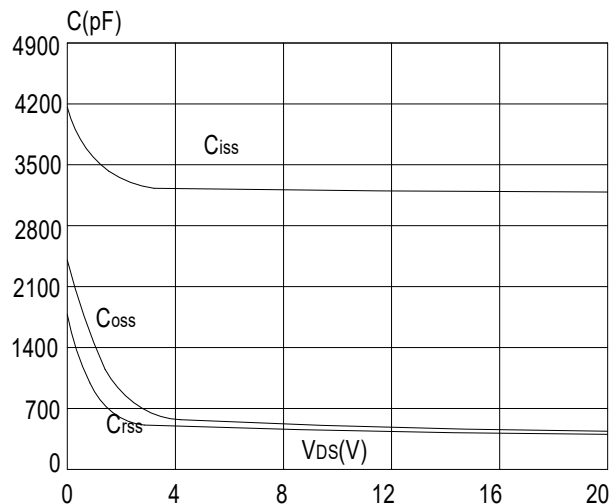




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

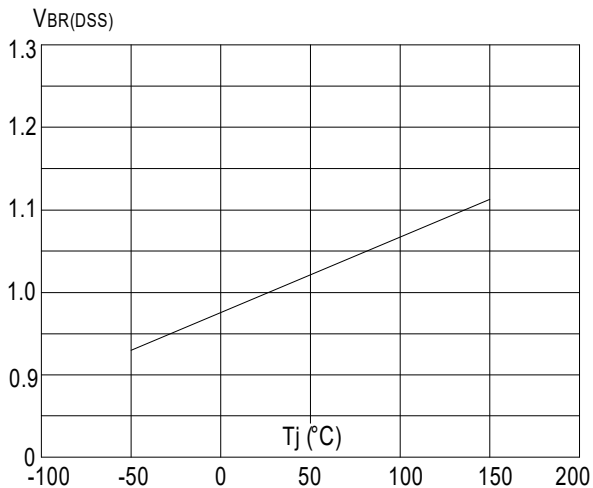


Figure 8: Normalized on Resistance vs. Junction Temperature

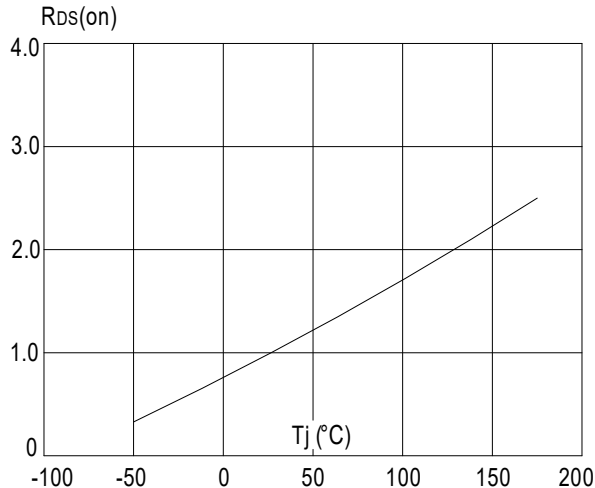


Figure 9: Maximum Safe Operating Area

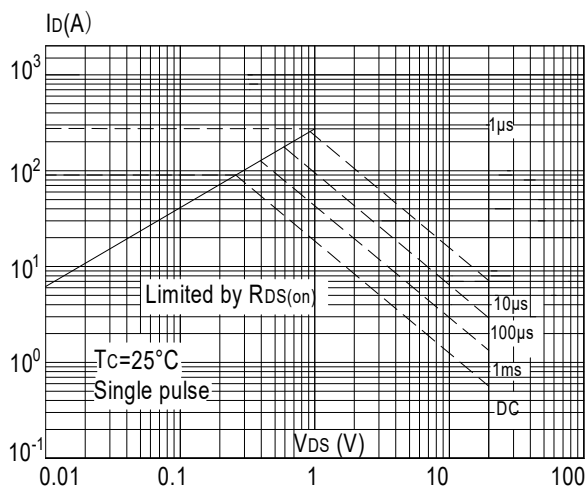


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

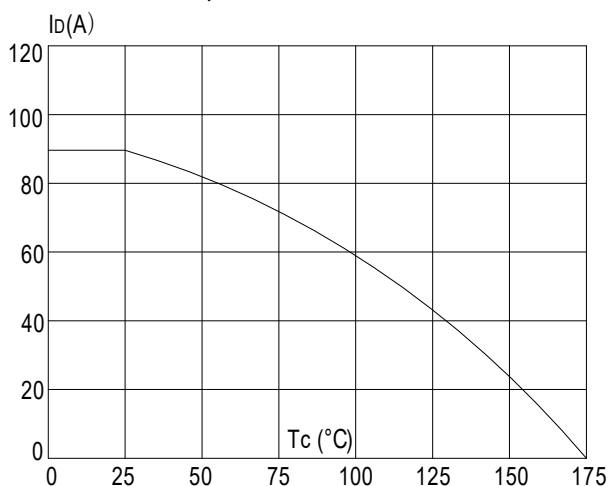
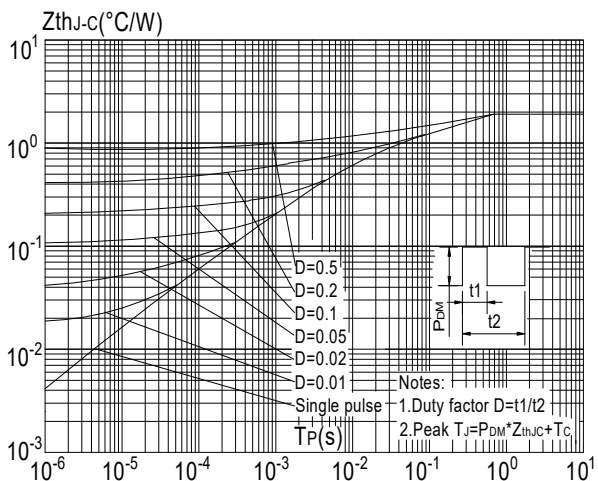
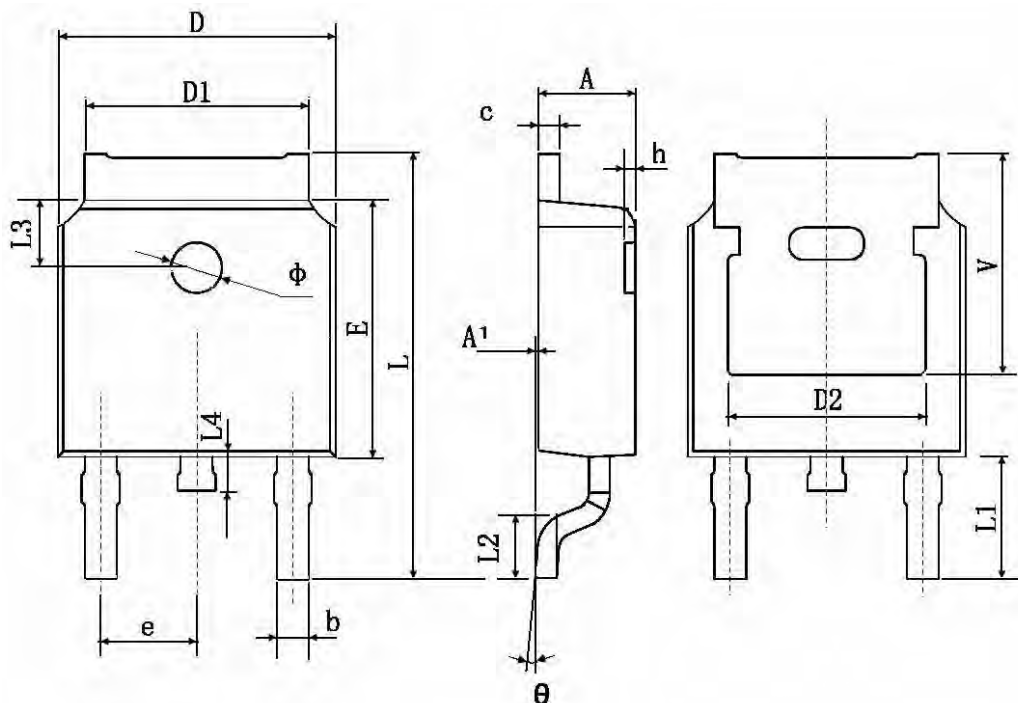


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case





TO252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	0.483 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	



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